

LISTING OF THE CLAIMS

This listing of claims, amended as indicated below, replaces all prior versions, and listings, of claims in the application

1. (Original) A method of forming a wire bond bonding a wire to a connection pad of an electronic device, comprising the steps of forming a first stitch bond on the connection pad, and forming a second stitch bond on the connection pad that is contiguous with the first stitch bond.
2. (Original) A method as claimed in claim 1, wherein the second stitch bond partially lies on the first stitch bond and partially lies on the connection pad.
3. (Original) A method as claimed in claim 1, wherein a position of the second stitch bond is offset from a position of the first stitch bond.
4. (Original) A method as claimed in claim 1, including arranging the second stitch bond such that it is oriented in a different direction relative to the orientation of the first stitch bond.
5. (Original) A method as claimed in claim 1, including arranging the second stitch bond such that it is oriented in a different direction relative to a length of wire connected to the wire bond.
6. (Original) A method as claimed in claim 1, wherein the wire is fed from a capillary, and including the step of moving the capillary in a reverse motion direction that is different to a direction that the first stitch bond is oriented after making the first stitch bond and before making the second bond.
7. (Original) A method as claimed in claim 6, including moving the capillary in a direction that is opposite to the reverse motion direction to a second stitch bonding position to form the second stitch bond.

8. (Original) A method as claimed in claim 1, including forming an additional stitch bond on the connection pad that is contiguous with the first stitch bond and/or second stitch bond.

9. (Original) A wire bond bonding a wire to a connection pad of an electronic device, comprising a first stitch bond on the connection pad and a second stitch bond on the connection pad that is contiguous with the first stitch bond.

10. (Original) A wire bond as claimed in claim 9, wherein the second stitch bond partially lies on the first stitch bond and partially lies on the connection pad.

11. (Original) A wire bond as claimed in claim 9, wherein a position of the second stitch bond is offset from a position of the first stitch bond.

12. (Original) A wire bond as claimed in claim 9, wherein the second stitch bond is oriented in a different direction relative to the orientation of the first stitch bond.

13. (Original) A wire bond as claimed in claim 9, wherein the second stitch bond is oriented in a different direction relative to a length of wire connected to the wire bond.

14. (Original) A wire bond as claimed in claim 9, including an additional stitch bond on the connection pad that is contiguous with the first stitch bond and/or second stitch bond.

15. (Canceled).

16. (New) A semiconductor device comprising:

a bond pad;

a wire;

a connection pad; and

a wire bond connecting the wire to the connection pad, wherein the wire bond comprises:

a first stitch bond on the connection pad and a second stitch bond on the connection pad that is contiguous with the first stitch bond.